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Read Statement

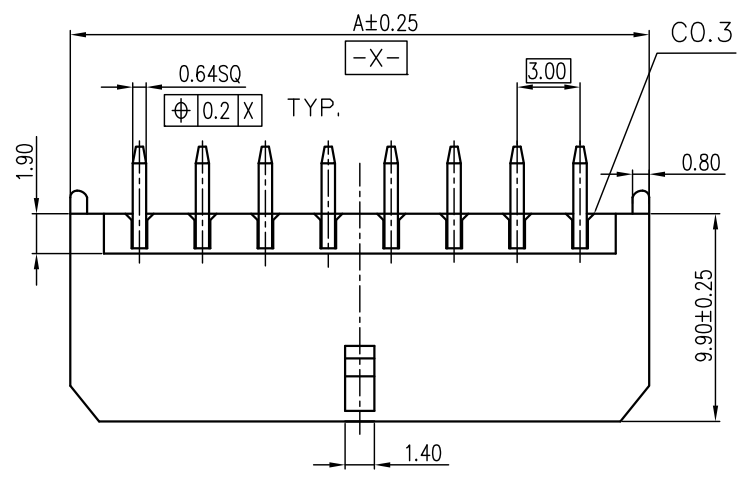
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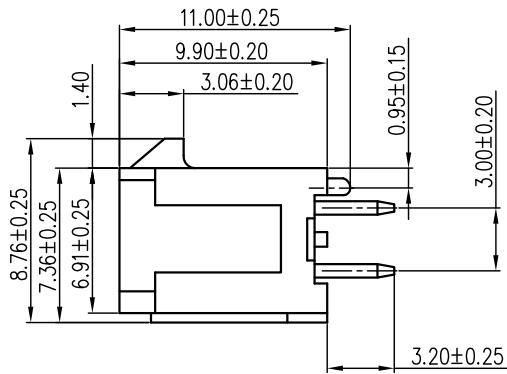
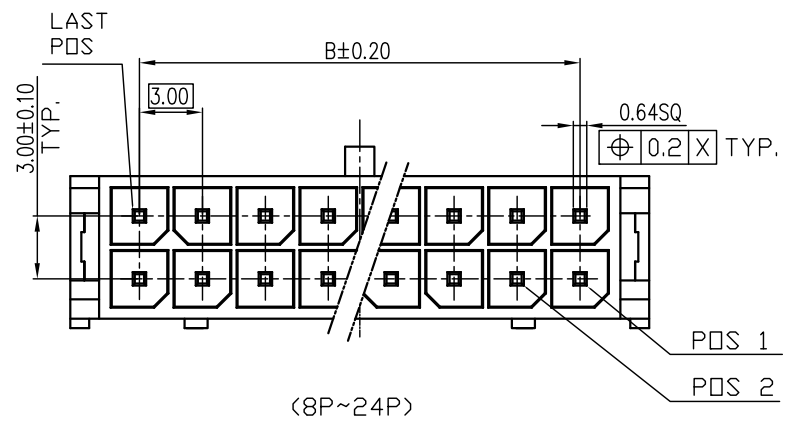
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

| REVISIONS | | | | |
|-----------|----------|---|------------|-----------|
| SYM | ECN No. | DESCRIPTION | DATE | APPROVED |
| A | NE-12149 | RELEASE FOR RoHS | 08/16/2012 | Arron Lin |
| B | NE-13034 | MODIFY PLATING TO OVERALL | 03/13/2013 | Arron Lin |
| CX1 | | UPDATE FOR 2 POS., PACKING QUANTITY AND PLATING | 03/03/2014 | Arron Lin |



- NOTE:
- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
 - CONTACT MATERIAL: COPPER ALLOY;
 - FINISH:
CONTACT AREA: SELECTIVE PLATING OPTIONS;
SOLDERING AREA: MATTE TIN PLATING 100 μ" MIN OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
 - THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
 - APPLICABLE P.C.BOARD THICKNESS: 1.60mm
 - PACKING MUST BE PER Amphenol PACKING SPECIFICATION



| | | |
|----------------|-------|-------|
| 24 | 39.60 | 33.00 |
| 22 | 36.60 | 30.00 |
| 20 | 33.60 | 27.00 |
| 18 | 30.60 | 24.00 |
| 16 | 27.60 | 21.00 |
| 14 | 24.60 | 18.00 |
| 12 | 21.60 | 15.00 |
| 10 | 18.60 | 12.00 |
| 08 | 15.60 | 9.00 |
| 06 | 12.60 | 6.00 |
| 04 | 9.60 | 3.00 |
| 02 | 6.60 | NA |
| NO. OF CIRCUIT | A | B |

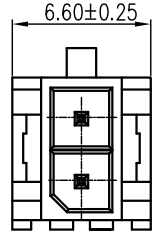
PART NO. G881AXX1X2T3EU
No. OF CIRCUIT

- CONTACT FINISH
- 0: Tin (OVERALL)
 - 1: FLASH GOLD (OVERALL)
 - 2: 15 μ" GOLD
 - 3: 30 μ" GOLD

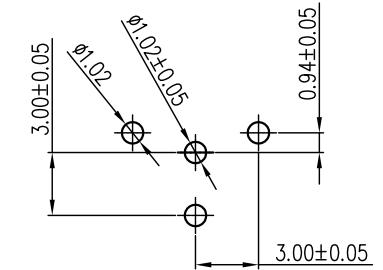
| TOLERANCE | APPROVALS | DATE | TITLE | | PART No. | | |
|----------------------------|--------------------|------------------|--|--------------|--|--|--|
| X. ±0.30 | DRAWN Debby Hung | 03/03/2014 | G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK | | Amphenol ® Amphenol Corporation Amphenol Taiwan Corporation | | |
| X.XX ±0.20 | CHECKED Roger Tsai | 03/03/2014 | | | | | |
| X.XXX ±0.10 | APPROVED Arron Lin | 03/03/2014 | | | | | |
| ANGULAR ±1° | DWG TYPE CUST DWG | PROJECT CODE PHD | UNIT mm | SIZE A3 | PART No. G881AXX1X2T3EU | | |
| UNLESS OTHERWISE SPECIFIED | | | SCALE NA | SHEET 1 OF 3 | DWG No. G881AXX1X2T3EU REV. CX1 | | |

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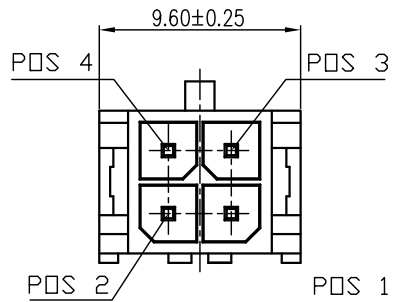
| REVISIONS | | | | |
|-----------|----------|---|------------|-----------|
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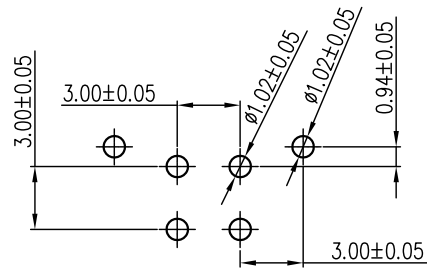
(2X1POS)



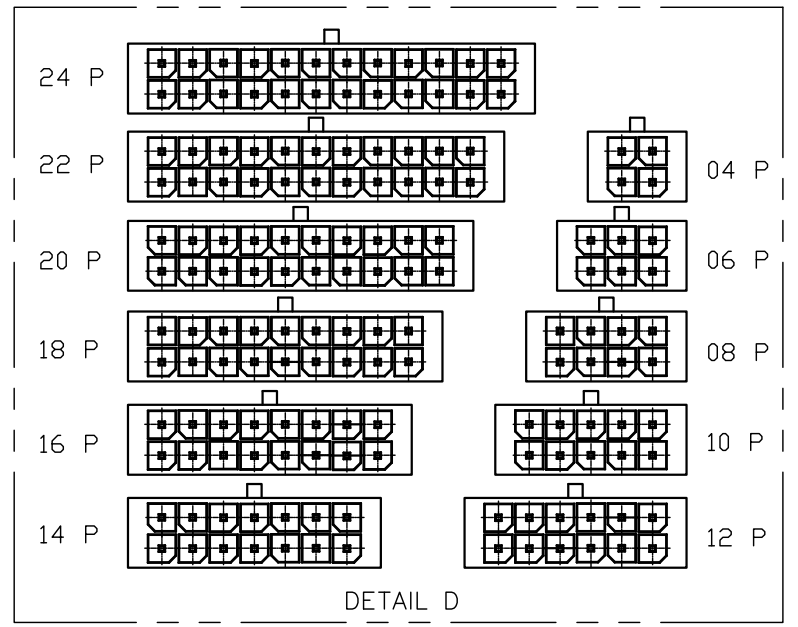
2X1 POSITIONS
RECOMMENDED PCB LAYOUT



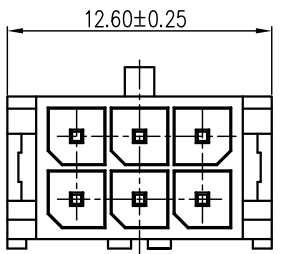
(2X2POS)



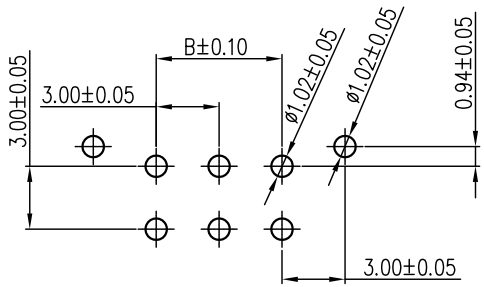
2X2 POSITIONS
RECOMMENDED PCB LAYOUT



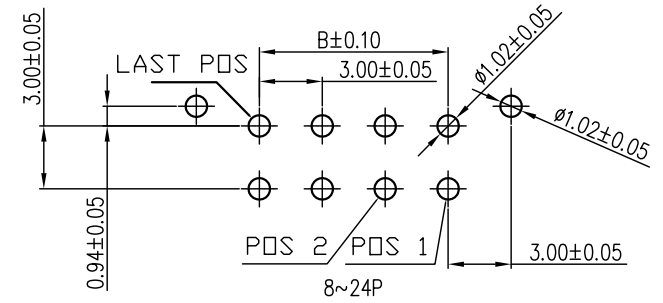
DETAIL D



(2X3POS)



2X3 POSITIONS
RECOMMENDED PCB LAYOUT



8~24P
RECOMMENDED PCB LAYOUT

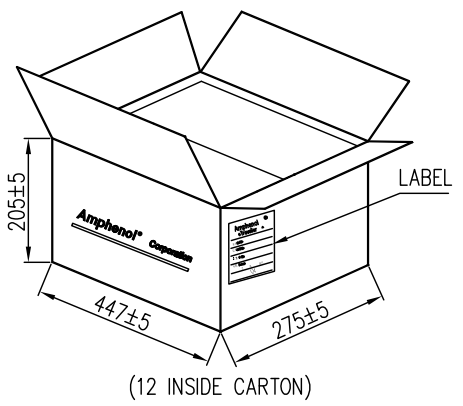
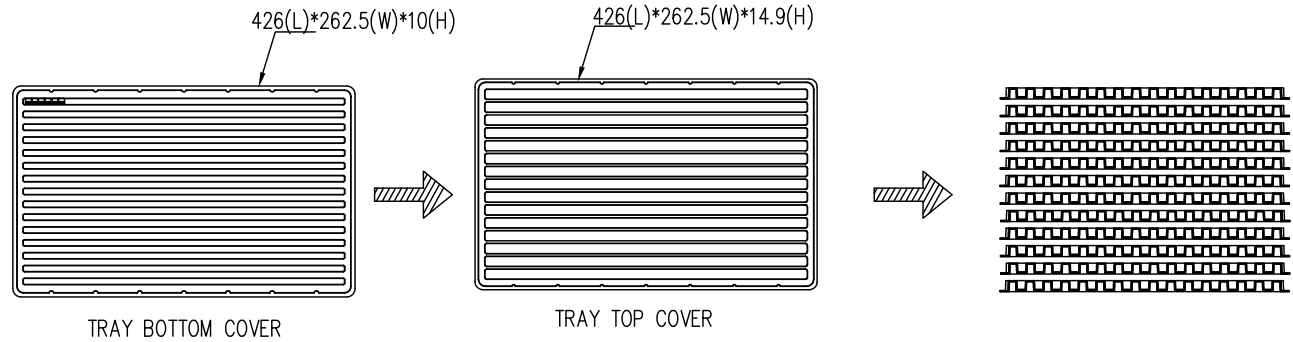
**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

| TOLERANCE | APPROVALS | DATE | TITLE | | Amphenol® | |
|----------------------------|--------------------|------------------|--|--------------|---|----------|
| X. ±0.30 | DRAWN Debby Hung | 03/03/2014 | G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK | | Amphenol Corporation Amphenol Taiwan Corporation | |
| X.X ±0.20 | CHECKED Roger Tsai | 03/03/2014 | | | | |
| X.XXX ±0.10 | APPROVED Arron Lin | 03/03/2014 | | | | |
| ANGULAR ±1° | DWG TYPE CUST DWG | PROJECT CODE PHD | UNIT mm | SIZE A3 | PART No. G881AXX1X2T3EU | |
| UNLESS OTHERWISE SPECIFIED | | | SCALE NA | SHEET 2 OF 3 | DWG No. G881AXX1X2T3EU | REV. CX1 |

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**PRELIMINARY RELEASE
SUBJECT TO CHANGE**



| POS | PCS/TRAY | PCS/CARTON |
|-----|----------|------------|
| 02 | 900 | 10800 |
| 04 | 615 | 7380 |
| 06 | 465 | 5580 |
| 08 | 375 | 4500 |
| 10 | 315 | 3780 |
| 12 | 270 | 3240 |
| 14 | 240 | 2880 |
| 16 | 210 | 2520 |
| 18 | 180 | 2160 |
| 20 | 165 | 1980 |
| 22 | 150 | 1800 |
| 24 | 150 | 1800 |

NOTE:
 1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

| TOLERANCE | APPROVALS | DATE | TITLE | | Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation | | |
|----------------------------|--------------------|------------------|--|----------|--|------------------------|-------------------------|
| X. ±0.30 | DRAWN Debby Hung | 03/03/2014 | G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK | | UNIT mm | SIZE A3 | PART No. G881AXX1X2T3EU |
| X.XX ±0.20 | CHECKED Roger Tsai | 03/03/2014 | | | | | |
| X.XXX ±0.10 | APPROVED Arron Lin | 03/03/2014 | | | | | |
| ANGULAR ±1° | DWG TYPE CUST DWG | PROJECT CODE PHD | | SCALE NA | SHEET 3 OF 3 | DWG No. G881AXX1X2T3EU | REV. CX1 |
| UNLESS OTHERWISE SPECIFIED | | | | | | | |